High-Q Capacitors (Microwave Chip Capacitors) [High-accuracy Types of High-frequency **Multilayer Chip Capacitors**]

Series ECD



Features

- Low Capacitance with tight tolerance. $(0.1 \text{ to } 15.0 \text{ pF}, \pm 0.05 \text{ pF to } \pm 5 \%)$
- High Q value / Low ESR at High Frequencies
- Ultra-Stable COG Performance (0 ± 30 ppm/°C)
- 0402/0201 Miniature Size $(0.10 \text{ to } 15.0 \text{ pF/}0.10 \text{ to } 2.0 \text{ pF, } \pm 0.05 \text{ pF, } \pm 0.075 \text{ pF etc})$

Applications

- At Microwave Frequencies
 - · Impedance Matching Circuit
 - · Resonant Circuit
 - · Coupling Circuit
- Application Examples
 - · RF modules, VCO, BPF, DUP, PA, etc.
 - · Cellular Phone, Bluetooth, Wireless LAN etc.

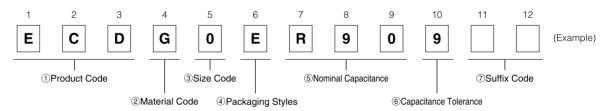
■ Product Code ECD:High-Q Capacitors

■ Precaution for Handling See Page 51 to 57

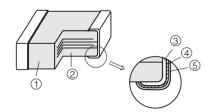
Packaging method

See Page 96

Explanation of Part Numbers



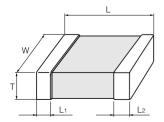
Construction



No	Name		
1	Ceramic dielectric		
2	Inner electrode		
3	Substrate electrode		
4	Intermediate electrode		
<u></u>	External electrode		

Unit · mm (inch)

■ Dimensions in mm (not to scale)



Code	Size Code (EIA)	L	W	Т	L ₁ , L ₂
Z	Type "06" (0201)	0.60±0.03	0.30±0.03	0.30±0.03	0.15±0.05
0	Type "10" (0402)	1.00±0.05	0.50±0.05	0.50±0.05	0.2±0.1

Panasonic

Multilayer Ceramic Capacitors

(High-accuracy Types of High-frequency) Multilayer Chip Capacitors

■ Packaging Styles

Code	Code Packaing Styles		Quantity	Type "06" (0201)	Type "10" (0402)
Code				T=0.3	T=0.5
E	φ 180 reel	Paper taping (Pitch : 2 mm)	pcs./reel	15,000 pcs. / reel	10,000 pcs. / reel

■ Temperature Coefficient

Characteristics	Temperature. Coefficient.
COG	0 ± 30 ppm/°C

These temperature coefficient are calculated between 20°C and 85°C

■ Rated Voltage

Rated Voltage	DC25V

■ Nominal Capacitance

Ex.	R10	1R0	2R7	120
Nominal Capacitance	0.10 pF	1.0 pF	2.7 pF	12 pF

■ Capacitance Tolerance

Size Code (EIA)	Tol. Code	Capacitance Range	Capacitance Tolerabce
T "OC"	8	0.10 to 0.50 pF	±0.05 pF
Type "06"	9	0.60 to 0.90 pF	±0.075 pF
(0201)	В	1.0 to 3.0 pF	±0.1 pF
	8	0.10 to 0.50 pF	±0.05 pF
T "10"	9	0.60 to 0.90 pF	±0.075 pF
Type "10"	В	1.0 to 3.0 pF	±0.1 pF
(0402)	С	3.3 to 10.0 pF	±0.25 pF
	J	12 to 15 pF	±5 %

■ Specification

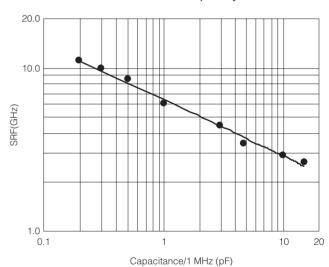
	Specification	Test Meth	od
Operating Temperature Range	–55 to 125 °C		
Rated Voltage	25 VDC		
Dielectric Withstanding Voltage	No break down	Test voltage:Rated voltage ×300 % Duration:1 to 5s Limit suge current:50 mA max.	
Insulation Resistance (I R)	More than 10000 $M\Omega$	Measuring voltage:Rated voltage Duration:60±5s Limit surge current:50 mA max.	
Cpacitance	Within the specified tolerance	Temperature:20 °C	
Dissipation Factor (tan δ)	tan $\delta \le 0.005$	Measuring frequency Measuring voltage:0.5	
Temperature Characteristics	C0G:0±30 ppm/ °C	Maximum capacitanc stage 1 to 5	e change at
		Stage	Temperature
		Stage 1	+20±2 °C
		Stage 2	–25±2 °C
		Stage 3 (Reference Temperature)	+20±2 °C
		Stage 4	+85±2 °C
		Stage 5	+20±2 °C
Adhesion	The terminal electrode shall be free from peeling or signs of peeling.	Soldering the specime jig shown in the figure, force to the arrow of seconds.	and apply at 5 N
		Sample	PC board
Bending Strength	Appearance:no mechanical damage	Sample Bending value:1 mm Bending speed:1 mm/	PC board
	Appearance:no mechanical damage	Bending value:1 mm	Sending Value
	Appearance:no mechanical damage More than 75 % of the soldered area of both terminal electrodes shall be covered with fresh solder.	Bending value:1 mm Bending speed:1 mm/	S value Sending Value O#20 °C
Strength	More than 75 % of the soldered area of both terminal	Bending value: 1 mm Bending speed: 1 mm/ 20 R340 R340 Solder temperature: 23 Dipping period: 4±1 s	S ending Value O#7 C O#7 C
Strength Solderability Resistance to Solder	More than 75 % of the soldered area of both terminal electrodes shall be covered with fresh solder. Appearance:no mechanical damage Capacitance change:	Bending value:1 mm Bending speed:1 mm/ 20 R340 R340 R340 Solder temperature:23 Dipping period:4±1 s Solder:H63A(JIS-Z-328 Solder temperature:27	Unit: mm O±5 °C 33) O±5 °C
Strength Solderability Resistance to Solder	More than 75 % of the soldered area of both terminal electrodes shall be covered with fresh solder. Appearance:no mechanical damage Capacitance change:	Bending value: 1 mm Bending speed: 1 mm/ 20 R340 R340 Solder temperature: 23 Dipping period: 4±1 s Solder: H63A(JIS-Z-328 Solder temperature: 27 Dipping period: 3.0±0.9	Unit:mm 0±5 °C 33) 0±5 °C 5 s
Strength Solderability Resistance to Solder	More than 75 % of the soldered area of both terminal electrodes shall be covered with fresh solder. Appearance:no mechanical damage Capacitance change:	Bending value:1 mm Bending speed:1 mm/ 20 R340 R340 R340 Solder temperature:23 Dipping period:4±1 s Solder:H63A(JIS-Z-328 Solder temperature:27 Dipping period:3.0±0.3	Unit: mm O±5 °C 33) O±5 °C
Strength Solderability Resistance to Solder	More than 75 % of the soldered area of both terminal electrodes shall be covered with fresh solder. Appearance:no mechanical damage Capacitance change:	Bending value: 1 mm Bending speed: 1 mm/ 20 R340 R340 A5±2 A5±2 Solder temperature: 23 Dipping period: 4±1 s Solder: H63A(JIS-Z-328 Solder temperature: 27 Dipping period: 3.0±0.8 Preheat condition: Temp.	O±5 °C O±5 °C Period

Characteristics	Specification	Test Method
Temperature cycle	Appearance:no mechanical damage IR:more than 1000 $\text{M}\Omega$ Capacitance change: Within $\pm 7.5~\%$ or $\pm 0.02~\text{pF}$ whichever is lager.	Condition of one cycle Step1:-55±3 °C 30±3 min. Step2:Room temp. 3 min. Step3:+125±3 °C 30±3 min. Step4:Room temp. 3 min. Number of cycles:5 Recovery:24±2 h
Moisture Resistance	Appearance:no mechanical damage IR:more than 1000 M Ω Capacitance change: Within ± 7.5 % or ± 0.02 pF whichever is lager. $\tan\delta \leq 0.005$	Temperature:40±2 °C Relative humidity:90 to 95 % Test period:500+24/0 h Recovery:24±2 h
Moisture Resistant Loading	Appearance:no mechanical damage IR:more than 1000 $\text{M}\Omega$	Temperature:40±2 °C Relative humidity:90 to 95 % Applied voltage:25 VDC Limit surge current:50 mA max. Test period:500+24/0 h Recovery:24±2 h
Loading at high temperature	Appearance:no mechanical damage IR:more than 10000 $\mbox{M}\Omega$	Temperature:+125 °C ±3 °C Applied voltage:50 VDC (Rated voltage ×200 %) Limit surge current:50 mA max. Test period:1000+48/0 h Recovery:24±2 h

■ Typical Performance Data

Q factor 2000 at 1GHz 1000 HiQ-Cap. o 100 Size:0402 15 Capacitance/1 MHz (pF)

Self Resonant Frequency



■ Standard Products for Type "06" (EIA "0201"), **Taped Version**

	Code	С	
Canaci	Rated voltage	DC	25V
Capaci- tance	Capacitance	Part No.	Dim T
	Tolerance		(mm)
0.1		ECDGZER108	0.3
0.2		ECDGZER208	0.3
0.3	±0.05 pF	ECDGZER308	0.3
0.4		ECDGZER408	0.3
0.5		ECDGZER508	0.3
0.6	±0.075 pF	ECDGZER609	0.3
0.7		ECDGZER709	0.3
8.0		ECDGZER809	0.3
0.9		ECDGZER909	0.3
1		ECDGZE1R0B	0.3
1.1		ECDGZE1R1B	0.3
1.2		ECDGZE1R2B	0.3
1.3		ECDGZE1R3B	0.3
1.5		ECDGZE1R5B	0.3
1.6	±0.1 pF	ECDGZE1R6B	0.3
1.8	±0.1 pi	ECDGZE1R8B	0.3
2		ECDGZE2R0B	0.3
2.2		ECDGZE2R2B	0.3
2.4		ECDGZE2R4B	0.3
2.7		ECDGZE2R7B	0.3
3		ECDGZE3R0B	0.3

Packaging Style Code: "E" for Taped Version (ø180 reel, Taping pitch: 2 mm)

■ Standard Products for Type "10" (EIA "0402"), Taped Version

	Code	С	
Capaci-	Rated voltage	DC	25V
tance	Capacitance	Part No.	Dim T
	Tolerance		(mm)
0.1		ECDG0ER108	0.5
0.2		ECDG0ER208	0.5
0.3	±0.05 pF	ECDG0ER308	0.5
0.4		ECDG0ER408	0.5
0.5		ECDG0ER508	0.5
0.6		ECDG0ER609	0.5
0.7	±0.075 pF	ECDG0ER709	0.5
0.8	±0.073 μι	ECDG0ER809	0.5
0.9		ECDG0ER909	0.5
1		ECDG0E1R0B	0.5
1.1		ECDG0E1R1B	0.5
1.2		ECDG0E1R2B	0.5
1.3	±0.1 pF	ECDG0E1R3B	0.5
1.5		ECDG0E1R5B	0.5
1.6		ECDG0E1R6B	0.5
1.8	±0.1 pi	ECDG0E1R8B	0.5
2		ECDG0E2R0B	0.5
2.2		ECDG0E2R2B	0.5
2.4		ECDG0E2R4B	0.5
2.7		ECDG0E2R7B	0.5
3		ECDG0E3R0B	0.5
3.3		ECDG0E3R3C	0.5
3.9		ECDG0E3R9C	0.5
4.7		ECDG0E4R7C	0.5
5.6	±0.25 pF	ECDG0E5R6C	0.5
6.8		ECDG0E6R8C	0.5
8.2		ECDG0E8R2C	0.5
10		ECDG0E100C	0.5
12	±5 %	ECDG0E120J	0.5
15	±5 %	ECDG0E150J	0.5

Packaging Style Code: "E" for Taped Version (\$\phi\$180 reel, Taping pitch: 2 mm)